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ABSTRACT**Nozzle for Soldering Apparatus**

In a dip soldering process, solder is pumped through a nozzle outlet. Leads of a component on a circuit board are dipped into the surface of the flowing solder to solder the leads to a track on the underside of the circuit board. To prevent solder bridging between the leads, a plate is provided below the solder surface, and passes between the leads. When withdrawing the leads from the solder, the solder surface is dropped to the level of the plate, so that excess solder is drawn away from the leads, preventing solder bridging between the leads. Member may be movable to rise through the solder surface as the circuit board is raised away from the surface.

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